



## ANSYS Certified For The Latest Generation Chip Technology

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PITTSBURGH, Sept. 17, 2015 /PRNewswire/ -- Customers of [TSMC](#) and [ANSYS](#) (NASDAQ: ANSS) can innovate the next generation of electronic devices – from smartphones to wearable technologies – thanks to TSMC's certification of ANSYS solutions. This certification enables customers to deliver their innovative products to market even faster while minimizing design costs and risk.



Today's modern electronic products are driven by markets that demand minimal power as well as high-performance and reliability. This is commonly achieved by integrating multiple functions into one system on a chip (SoC). Designing a SoC has become increasingly time consuming and resource intensive as semiconductor technology continues to miniaturize. The TSMC certification ensures the required accuracy and proven design process for customers and significantly minimizes risk in SoC design, allowing innovative new devices to be more affordable for consumers.

TSMC's certification of ANSYS<sup>®</sup>RedHawk<sup>™</sup> and Totem<sup>™</sup> solutions for its 10nm FinFET chip enables designers to address the power integrity and reliability requirements for chip applications. The certification is based on the most current version of TSMC's 10nm semiconductor version 0.9 process technology. TSMC's certification and reference flow provides static and dynamic voltage drop analysis and advanced signal and power electromigration verification to meet TSMC's 10nm requirements – enabling users to innovate the next generation of SoC designs for use in emerging mobile, computing and networking applications.

"The joint delivery of reference flow and the certification of RedHawk and Totem for TSMC 10nm FinFET technology enable our mutual customers to design complex SoCs with built-in reliability," said John Lee, general manager, ANSYS. "Our long and successful track record of technical alliance with TSMC is continuing to drive the creation and delivery of advanced power integrity and reliability solutions that adequately and accurately address the needs of TSMC's emerging silicon technology, enabling customers to innovate at the design level."

"We have closely collaborated with ANSYS to enable the delivery of advanced power integrity solutions including the analysis of thermal effects in 10nm FinFET technology," said Suk Lee, TSMC senior director, design infrastructure marketing division. "The certification of RedHawk and Totem for 10nm FinFET technology ensures tool readiness, and allows customers to analyze and design power delivery networks with confidence."

The ANSYS portfolio of product offerings will be showcased at [TSMC OIP Ecosystem Forum](#) on Sept. 17 in Santa Clara, California.

### About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs over 2,750 professionals, many of them expert in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit [www.ansys.com](http://www.ansys.com) for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: [www.ansys.com/Social@ANSYS](http://www.ansys.com/Social@ANSYS)

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